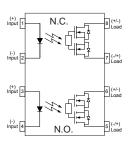
# **SUPSiC®**

Parameter	Symbol	Rating	Units	
Load Voltage	VL	400	V	
Load Current	lL l	0.12	Α	
On-Resistance	Ron	20	Ω	
I/O Isolation Voltage	V/ıo	5000	Vrms	



DIP-8



1,3. LED Anode 2,4, LED Cathode

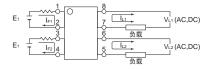
5,6. Drain (MOS FET)

7,8. Drain (MOS FET)

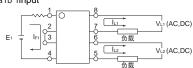








#### (2) 1a1b 1input



SUPSiC PhotoRelays

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- · resistant to vibration and impact AC or DC load
- switching
- Small package size

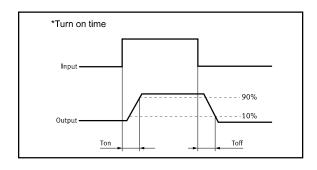
#### **Applications**

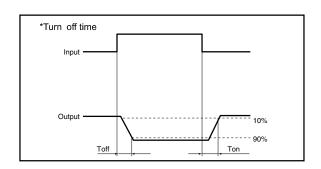
- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

#### **TPYES**

Catagami	Outp	Output Rating		Dort No.	Packing Quantity	
Category	Load Voltage	Load Current	Package Part No.			
AC/DC 400V		400 4	DIP-8	GAQW614E	50pcs /tube	
AO/BO	400V	120mA	SMD-8	GAQW614EH	1000pcs /reel	







## Absolute Maximum Ratings (Ta = 25°C)

	Item	Symbol	Value	Units	Note
	Continuous LED Current	IF	50	mA	
Input	Peak LED Current	IFP	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	Pln	75	mW	
Load Voltage		VL	400	V(AC peak or DC)	
Output	Load Current	IL	120	mA	
	Peak Load Current	IPeak	0.6	Α	1ms(1 pulse)
	Output Power Dissipation	Pout	450	mW	
Total Power D	Dissipation	PT	500	mW	
I/O Isolation Vo	oltage	VI/O	5000	Vrms	RH=60%, 1min
Operating Ter	mperature	TOpr	-40 to +85	-40 to +85	
Storage Temp	perature	TStg	-40 to +100	-40 to +100	
Pin Soldering	Temperature	TSol	260	260	10 sec max.

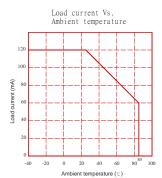
#### Electrical Characteristics (Ta = 25°C)

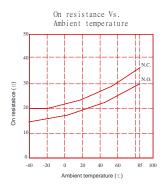
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	V <sub>F</sub>		1.2	1.5	V	I <sub>F</sub> =10mA
Input	Operation LED Current	F On		0.5	5.0	mA	
	Recovery LED Current	<b>I</b> F Off		0.35	0.5	mA	
	Recovery LED Voltage	V <sub>F</sub> off	0.5			V	
	On-Resistance	Ron		20(N.O.)	30(N.O.)	Ω	I <sub>F</sub> =5mA (N.O.) I <sub>F</sub> =0mA (N.C) I <sub>L</sub> =100mA Time to flow is within 1 sec.
Output				20(N.C.)	50(N.C.)		Time to now a within 1 sec.
	Off-State Leakage Current	ILeak			<b>1</b> (N.O.)	uA	I <sub>F</sub> =0mA (N.O.) I <sub>F</sub> =5mA (N.C) V <sub>L</sub> = Rating
					10(N.C.)		
	Output Capacitance	Cout		150		pF	I₅=5mA,V∟=0, f=1MHz
Transmis sion	Turn-On Time	Ton		0.23 (N.O.)	0.5 (N.O.)	ms	
				0.2 (N.C.)	1.0 (N.C.)		I⊧=5mA, I∟=Max
	Turn-Off Time	Tof		0.03 (N.O.)	0.2(N.O.)	ms	
				0.5 (N.C.)	3.0 (N.C.)		
Coupled	I/O Isolation Resistance	R <sub>I/O</sub>	1010			Ω	DC500V
Coupled	I/O Capacitance	C <sub>I/O</sub>		0.8		pF	f=1MHz

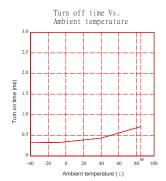
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

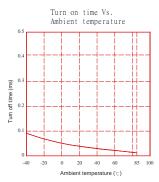


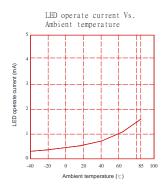
#### **Engineering Data**

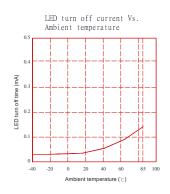


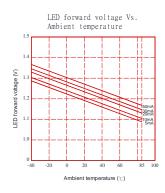


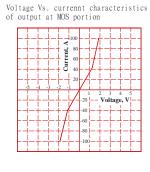


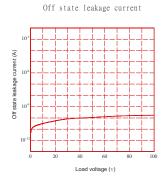


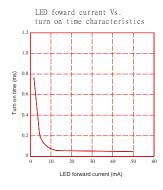


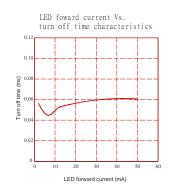


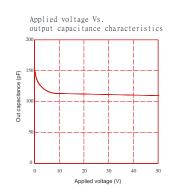










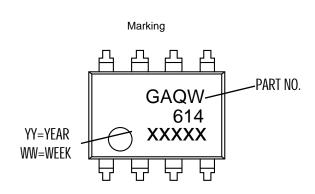


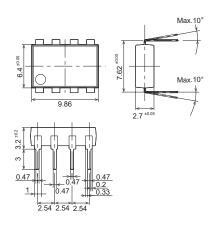


**Dimensions and DIP-8 Package** 

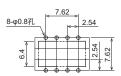
Unit: mn

#### Through hole terminal type





PC board pattern (Bottom view)



DIP Tape dimensions Unit: mm

Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

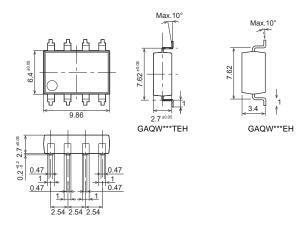




# Dimensions and SMD-8 Package Unit: mm

# Marking GAQW 614 YY=YEAR WW=WEEK WEEK

#### Surface mount terminal type



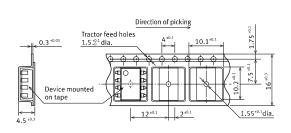
# Recommended mounting pad

(Top view)

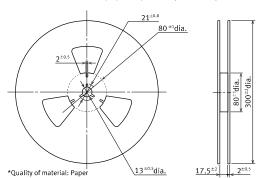


#### Tape dimensions (tape reel)

Tape dimensions (Unit: mm)



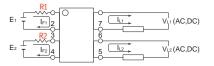
#### Dimensions of paper tape reel (Unit: mm)





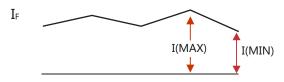
# **Using Methods**

Examples of resistance value to control LED forward current (IF=5mA)



E1 E2	R1 R2(Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA, at I(MIN), and less than 30mA, at I(MAX).



#### **Recommended Operating Conditions**

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

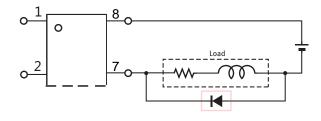
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	lF	5.0	7.0	30	mA

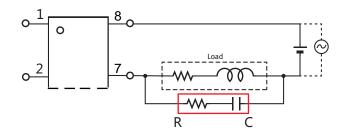
#### **Protection Circuit**

Output spike voltages:if an inductive load generates spike voltages which exceed heabsolute maximum rating, the spike voltage shall be limited.

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



#### **Recommended Soldering Conditions**

# (a) Infrared reflow soldering:

■ Peak reflow soldering : 260°C or below (package surface temperature)

Time of peak reflow temperature : 10 sec
 Time of temperature higher than 230°C : 30-60 sec
 Time to preheat temperature from 180~190°C : 60-120 sec

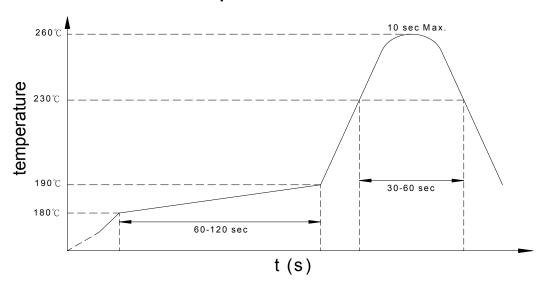
■ Time(s) of reflow: Two

■ Flux: Rosin flux containing small amount of chlorine (The

flux with a maximum chlorine content of 0.2 Wt% is

recommended.)

# Recommended Temperature Profile of Infrared Reflow



# (b) Wave soldering:

■ Temperature : 260°C or below (molten solder temperature)

■ Time : 10 seconds or less

■ Preheating conditions : 120°C or below (package surface temperature)

■ Time(s) of reflow : One

■ Flux: Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

## (c) Cautions:

■ Fluxes: Avoid removing the residual flux with freon-based and chlorine-based

cleaning solvent.

Avoid shorting between portion of frame and leads.